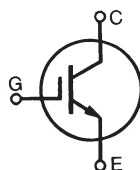


## High Voltage IGBT

## IXGA20N250HV

## For Capacitor Discharge Applications



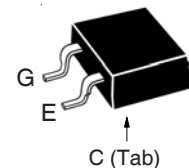
$$V_{CES} = 2500V$$

$$I_{C110} = 12A$$

$$V_{CE(sat)} \leq 3.1V$$

Symbol	Test Conditions	Maximum Ratings	
$V_{CES}$	$T_J = 25^\circ\text{C to } 150^\circ\text{C}$	2500	V
$V_{CGR}$	$T_J = 25^\circ\text{C to } 150^\circ\text{C}, R_{GE} = 1M\Omega$	2500	V
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ\text{C}$	30	A
$I_{C110}$	$T_C = 110^\circ\text{C}$	12	A
$I_{CM}$	$T_C = 25^\circ\text{C}, V_{GE} = 19V, 1ms$ 10ms	105 55	A A
<b>SSOA</b>	$V_{GE} = 15V, T_{VJ} = 125^\circ\text{C}, R_G = 20\Omega$	$I_{CM} = 60$	A
<b>(RBSOA)</b>	Clamped Inductive Load	1500	V
$P_C$	$T_C = 25^\circ\text{C}$	150	W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{JM}$		150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering	300	$^\circ\text{C}$
$T_{SOLD}$	1.6 mm (0.062in.) from Case for 10s	260	$^\circ\text{C}$
$V_{ISOL}$	50/60Hz, 1 Minute	4000	V~
<b>Weight</b>		2.3	g

## TO-263



G = Gate      C = Collector  
E = Emitter    Tab = Collector

## Features

- International Standard Package
- High Voltage Package
- Electrically Isolated Tab
- High Peak Current Capability
- Low Saturation Voltage
- Molding Epoxies Meet UL 94 V-0 Flammability Classification

## Advantages

- High Power Density
- Easy to Mount

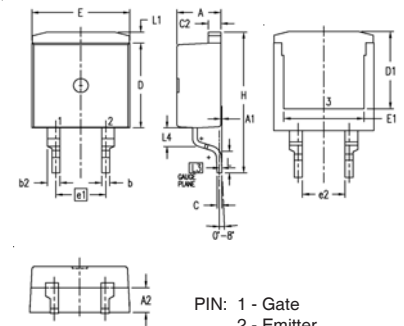
## Applications

- Capacitor Discharge
- Pulsar Circuits

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$BV_{CES}$	$I_C = 250\mu\text{A}, V_{GE} = 0V$	2500		V
$V_{GE(th)}$	$I_C = 250\mu\text{A}, V_{CE} = V_{GE}$	3.0		5.0 V
$I_{CES}$	$V_{CE} = 0.8 \cdot V_{CES}, V_{GE} = 0V$ $T_J = 125^\circ\text{C}$			25 $\mu\text{A}$ 750 $\mu\text{A}$
$I_{GES}$	$V_{CE} = 0V, V_{GE} = \pm 20V$			$\pm 100$ nA
$V_{CE(sat)}$	$I_C = 20A, V_{GE} = 15V, \text{Note 1}$			3.1 V

Symbol	Test Conditions ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Specified)	Characteristic Values		
		Min.	Typ.	Max.
$g_{fs}$	$I_C = 20\text{A}$ , $V_{CE} = 10\text{V}$ , Note 1	8	13	S
$I_{C(ON)}$	$V_{GE} = 20\text{V}$ , $V_{CE} = 15\text{V}$ , Note 1		190	A
$C_{ies}$	$V_{CE} = 15\text{V}$ , $V_{GE} = 25\text{V}$ , $f = 1\text{MHz}$		1190	pF
$C_{oes}$			53	pF
$C_{res}$			18	pF
$Q_g$	$I_C = 20\text{A}$ , $V_{GE} = 15\text{V}$ , $V_{CE} = 1000\text{V}$		53	nC
$Q_{ge}$			8	nC
$Q_{gc}$			22	nC
$t_{d(on)}$	<b>Resistive Switching Times</b> $I_C = 40\text{A}$ , $V_{GE} = 15\text{V}$ , Note 1 $V_{CE} = 1250\text{V}$ , $R_G = 10\Omega$		57	ns
$t_r$			160	ns
$t_{d(off)}$			136	ns
$t_f$			930	ns
$R_{thJC}$				0.83 $^\circ\text{C/W}$

## TO-263 (HV) Outline



SYM	INCHES		MILLIMETER	
	MIN	MAX	MIN	MAX
A	.170	.185	4.30	4.70
A1	.000	.008	0.00	0.20
A2	.091	.098	2.30	2.50
b	.028	.035	0.70	0.90
b2	.046	.054	1.18	1.38
C	.018	.024	0.45	0.60
C2	.049	.055	1.25	1.40
D	.354	.370	9.00	9.40
D1	.311	.327	7.90	8.30
E	.386	.402	9.80	10.20
E1	.307	.323	7.80	8.20
e1	.200 BSC		5.08 BSC	
(e2)	.163	.174	4.13	4.43
H	.591	.614	15.00	15.60
L	.079	.102	2.00	2.60
L1	.039	.055	1.00	1.40
L3	.010 BSC		0.254 BSC	
(L4)	.071	.087	1.80	2.20

Note 1. Pulse test,  $t < 300\mu\text{s}$ , duty cycle,  $d < 2\%$ .

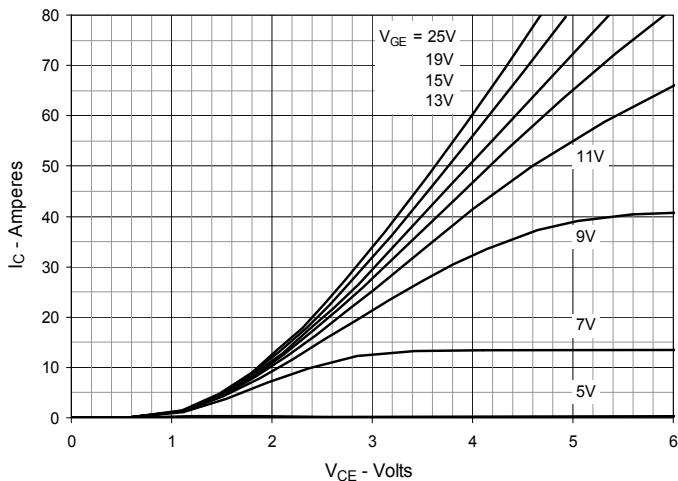
### PRELIMINARY TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

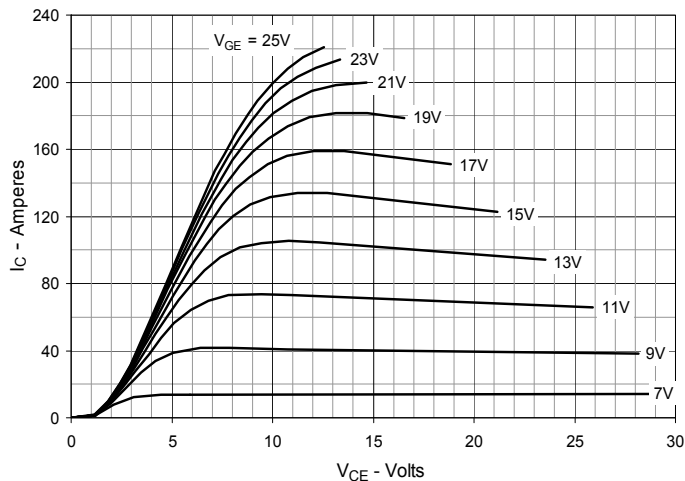
IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,931,844 5,049,961 5,237,481 6,162,665 6,404,065 B1 6,683,344 6,727,585 7,005,734 B2 7,157,338B2  
4,860,072 5,017,508 5,063,307 5,381,025 6,259,123 B1 6,534,343 6,710,405 B2 6,759,692 7,063,975 B2  
4,881,106 5,034,796 5,187,117 5,486,715 6,306,728 B1 6,583,505 6,710,463 6,771,478 B2 7,071,537

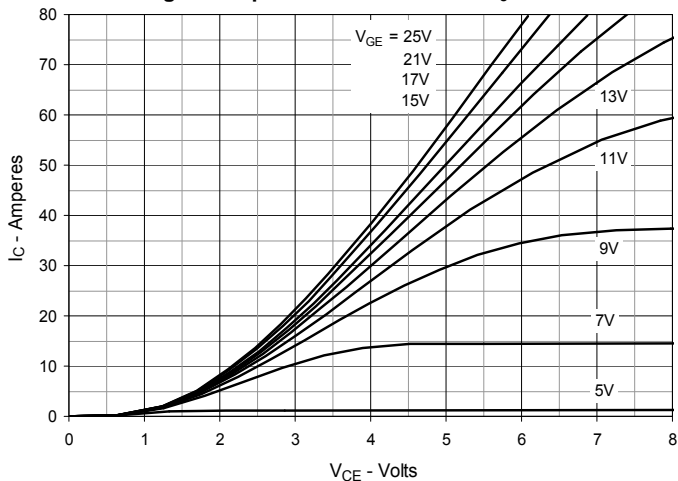
**Fig. 1. Output Characteristics @  $T_J = 25^\circ\text{C}$**



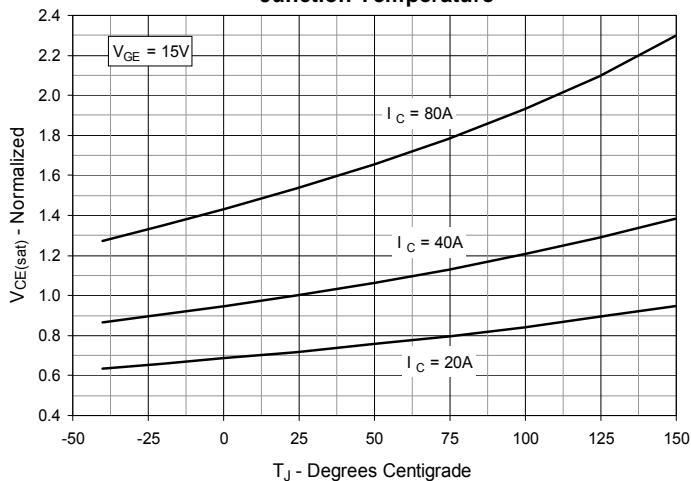
**Fig. 2. Extended Output Characteristics @  $T_J = 25^\circ\text{C}$**



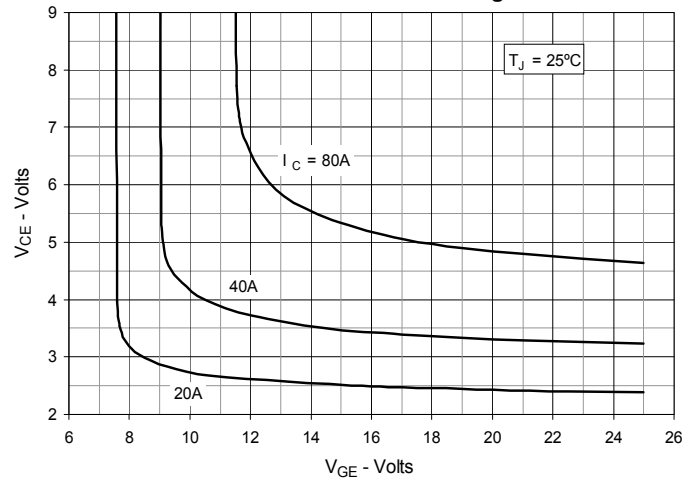
**Fig. 3. Output Characteristics @  $T_J = 125^\circ\text{C}$**



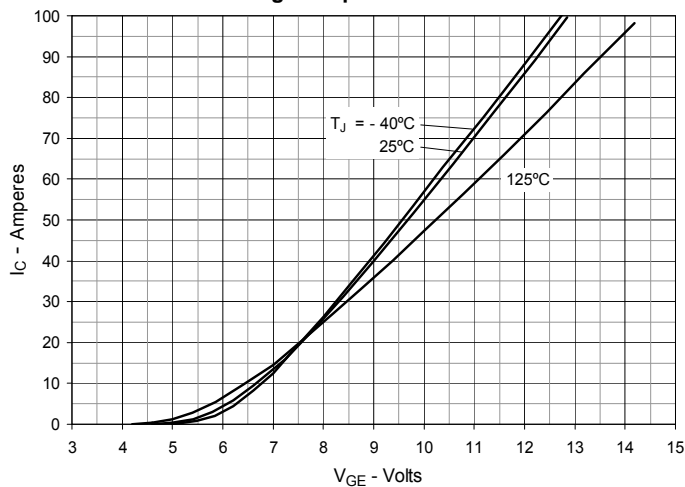
**Fig. 4. Dependence of  $V_{CE(sat)}$  on Junction Temperature**



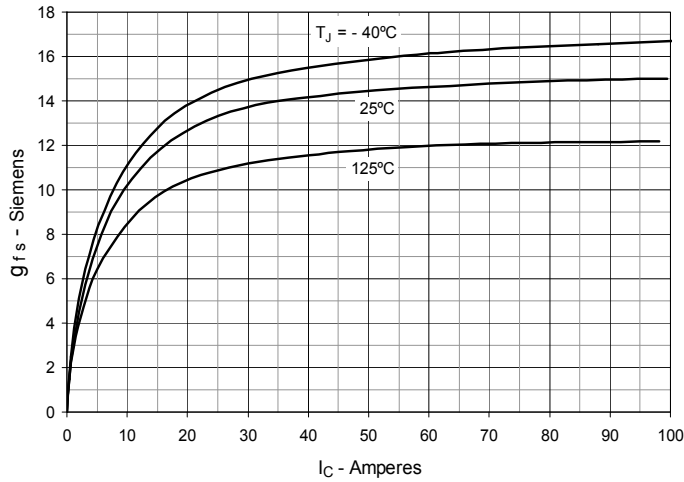
**Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage**



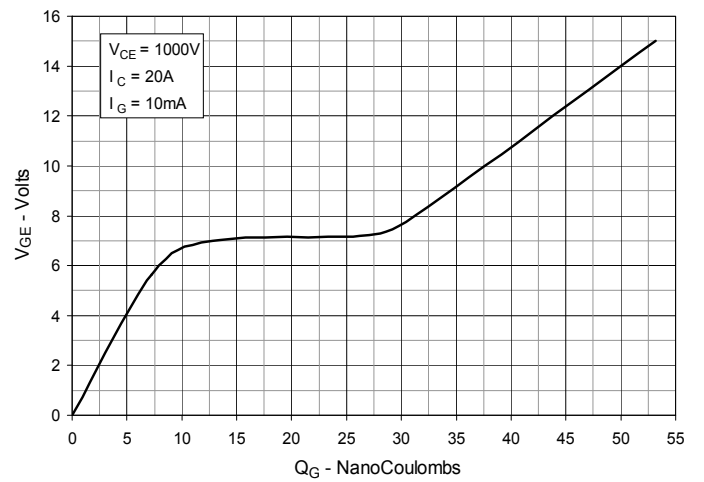
**Fig. 6. Input Admittance**



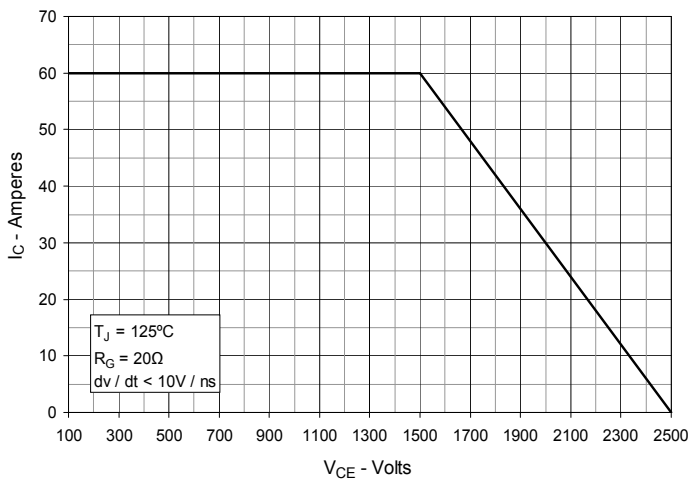
**Fig. 7. Transconductance**



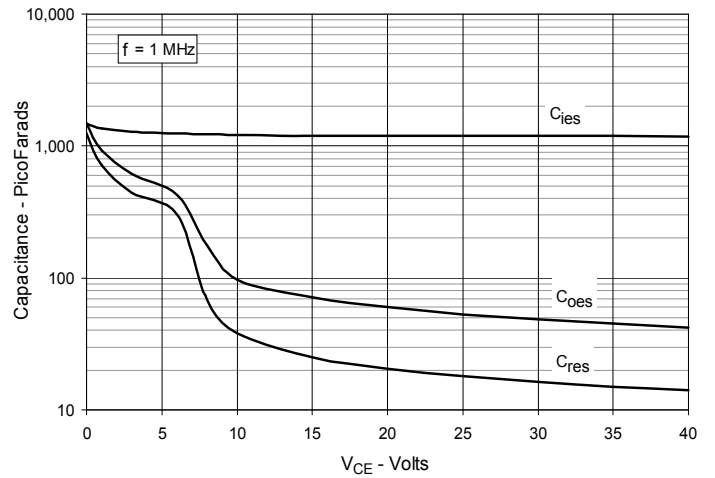
**Fig. 8. Gate Charge**



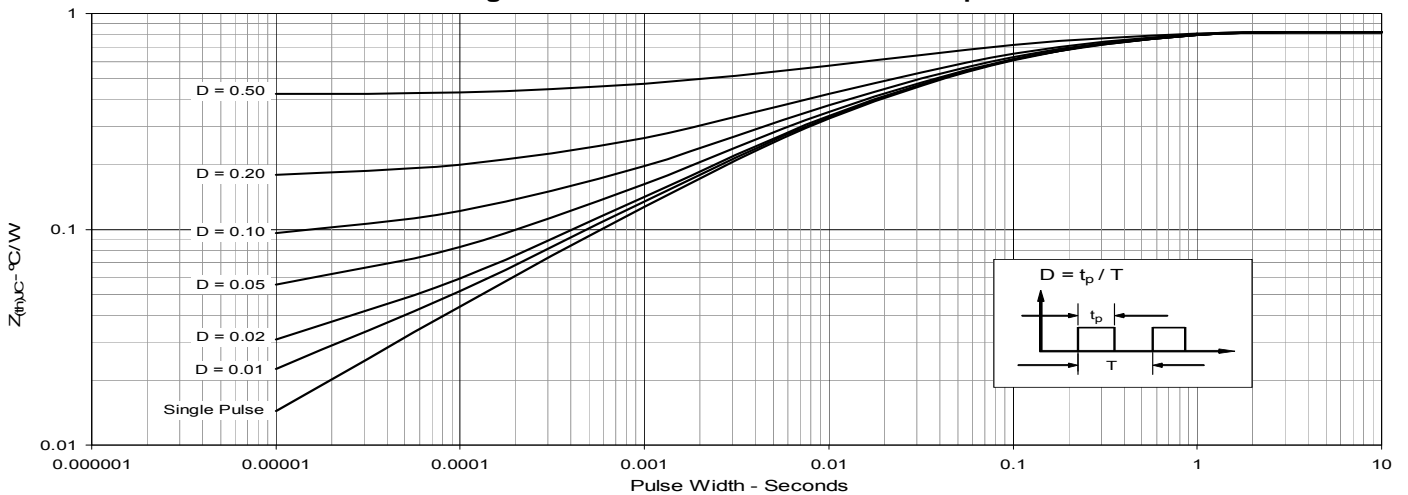
**Fig. 9. Reverse-Bias Safe Operating Area**



**Fig. 10. Capacitance**

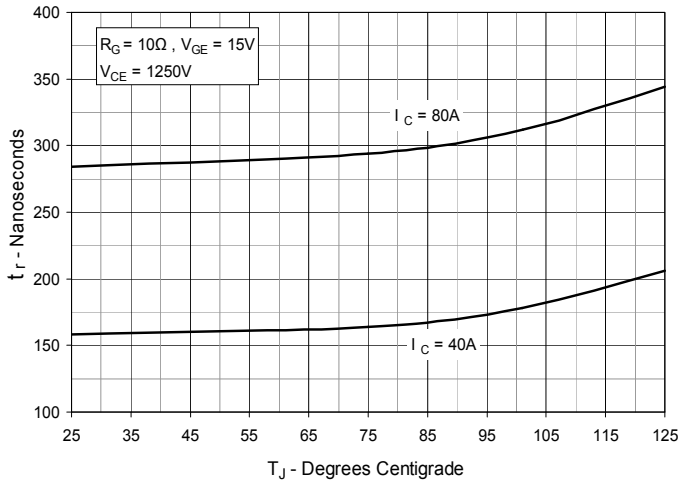


**Fig. 13. Maximum Transient Thermal Impedance**

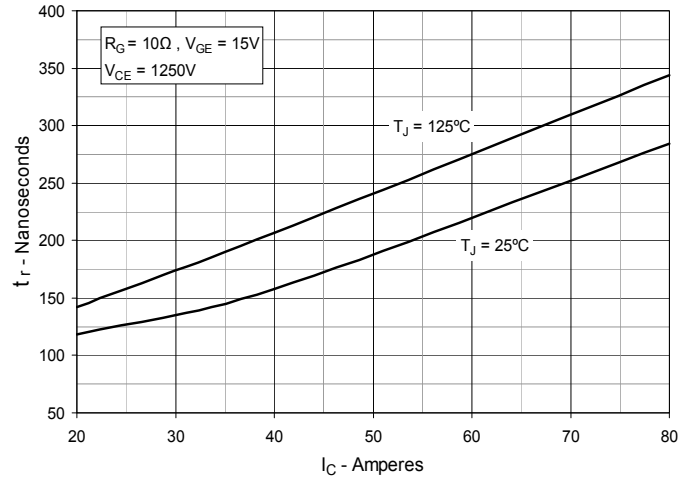


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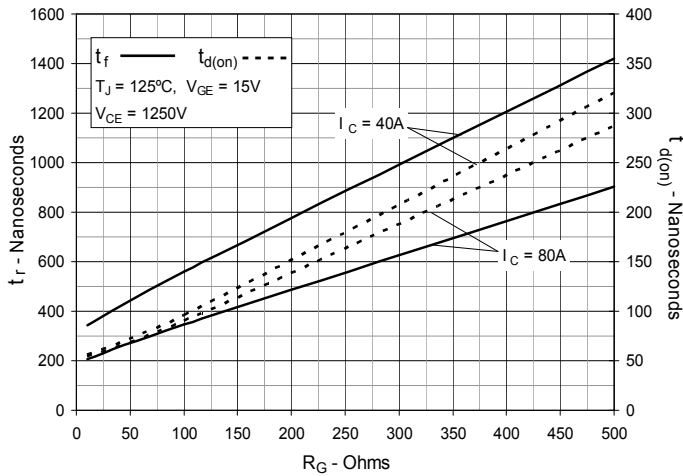
**Fig. 12. Resistive Turn-on Rise Time vs. Junction Temperature**



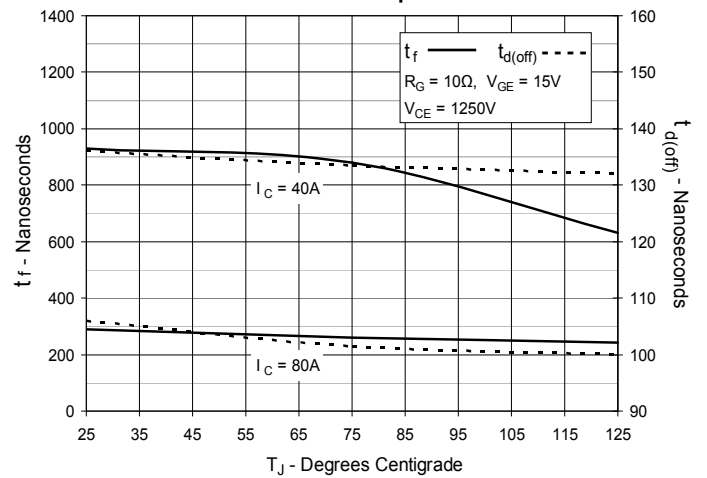
**Fig. 13. Resistive Turn-on Rise Time vs. Collector Current**



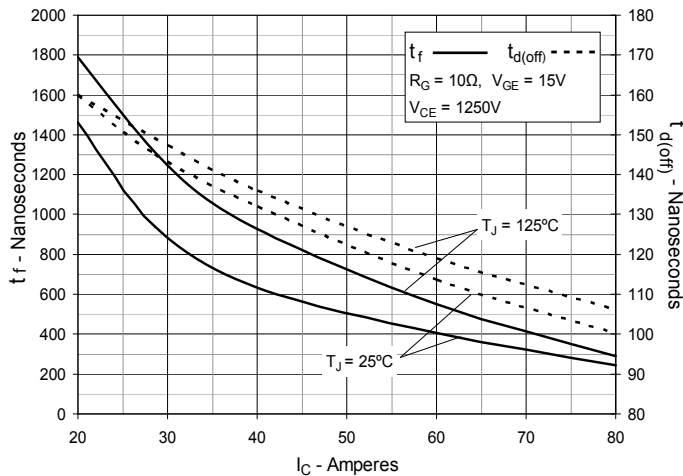
**Fig. 14. Resistive Turn-on Switching Times vs. Gate Resistance**



**Fig. 15. Resistive Turn-off Switching Times vs. Junction Temperature**



**Fig. 16. Resistive Turn-off Switching Times vs. Collector Current**



**Fig. 17. Resistive Turn-off Switching Times vs. Gate Resistance**

